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4-, 6- and 8-Channel EMI Filter Arrays with ESD Protection

CM1636

Features

- Four, six and eight channels of EMI filtering with integrated ESD protection
- Pi-style EMI filters in a capacitor-resistorcapacitor (C-R-C) network
- ±15kV ESD protection on each channel (IEC 61000-4-2 Level 4, contact discharge)
- ±30kV ESD protection on each channel (HBM)
- Greater than 30dB of attenuation from 800MHz to 3GHz
- UDFN package with 0.40mm lead pitch:
 - •4-ch. = 8-lead UDFN
 - •6-ch. = 12-lead UDFN
 - •8-ch. = 16-lead UDFN
- Tiny UDFN package size:
 - 8-lead: 1.7mm x 1.35mm x 0.50mm
 - 12-lead: 2.5mm x 1.35mm x 0.50mm
 - 16-lead: 3.3mm x 1.35mm x 0.50mm
- Increased robustness against vertical impacts during manufacturing process
- Lead-free finishing

Applications

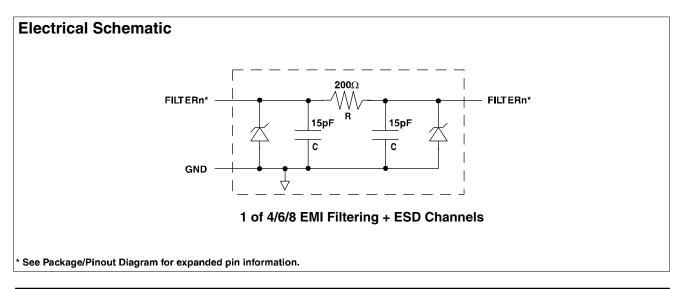
- I/O port protection for mobile handsets, notebook computers, PDAs etc.
- EMI filtering for data ports in cell phones, PDAs or notebook computers.
- EMI filtering for LCD, camera and chip-to-chip data lines

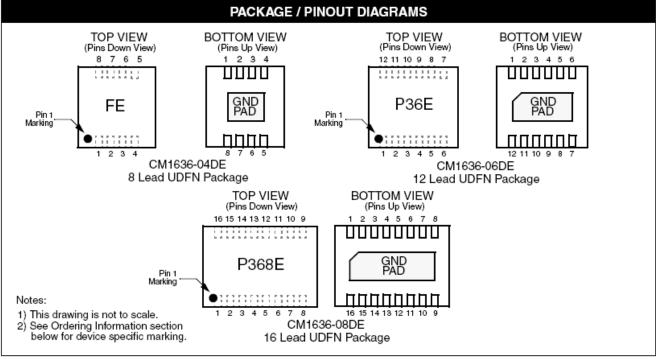
Product Description

The CM1636 is an EMI filter array with ESD protection, which integrates either four, six or eight pi filters (C-R-C). Each CM1636 filter has component values of 15pF-200W-15pF. These parts include ESD protection diodes on every pin, providing a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD diodes connected to the filter ports safely dissipate ESD strikes of ±15kV contact discharge, twice the specification requirement of the IEC 61000-4-2, Level 4 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than ±30kV.

This device is particularly well-suited for portable electronics (e.g. mobile handsets, PDAs, notebook computers) because of its small package and easy-to-use pin assignments. In particular, the CM1636 is ideal for EMI filtering and protecting data lines from ESD in wireless handsets.

The CM1636 is available in space-saving, ultra-low-profile, 8-lead, 12-lead and 16-lead 0.4mm pitch UDFN packages. It is fabricated with California Micro Devices' *Centurion*TM process and available with lead-free finishing.





	PIN DESCRIPTIONS												
	Pins					Pins							
1636- 04Dx	1636- 06Dx	1636- 08Dx	NAME	DESCRIPTION	1636- 04Dx	1636- 06Dx	1636- 08Dx	NAME	DESCRIPTION				
1	1	1	FILTER1	Filter Channel 1	8	12	16	FILTER1	Filter Channel 1				
2	2	2	FILTER2	Filter Channel 2	7	11	15	FILTER2	Filter Channel 2				
3	3	3	FILTER3	Filter Channel 3	6	10	14	FILTER3	Filter Channel 3				
4	4	4	FILTER4	Filter Channel 4	5	9	13	FILTER4	Filter Channel 4				
	5	5	FILTER5	Filter Channel 5		8	12	FILTER5	Filter Channel 5				
	6	6	FILTER6	Filter Channel 6		7	11	FILTER6	Filter Channel 6				
		7	FILTER7	Filter Channel 7			10	FILTER7	Filter Channel 7				
		8	FILTER8	Filter Channel 8			9	FILTER8	Filter Channel 8				
	GND Pad		GND	Device Ground									

Ordering Information

PART NUMBERING INFORMATION								
		Lead-free Finish						
Leads/Pins	Package	Ordering Part Number ¹	Part Marking					
8	UDFN-08	CM1636-04DE	FE					
12	UDFN-12	CM1636-06DE	P36E					
16	UDFN-16	CM1636-08DE	P368E					

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

Specifications

ABSOLUTE MAXIMUM RATINGS									
PARAMETER	RATING	UNITS							
Storage Temperature Range	-65 to +150	°C							
DC Power per Resistor	100	mW							
Package DC Power Rating	300	mW							

STANDARD OPERATING CONDITIONS								
PARAMETER	RATING	UNITS						
Operating Temperature Range	-40 to +85	°C						

	ELECTRICAL	OPERATING CHARACTE	RISTIC	S (SEE NOT)	E 1)	
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
R	Resistance		160	200	240	Ω
C _{TOTAL}	Total Channel Capacitance	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	24	30	36	pF
С	Capacitance	At 2.5V DC, 1MHz, 30mV AC		15		pF
V _{DIODE}	Diode Standoff Voltage	$I_{\text{DIODE}} = 10 \mu A$		6.0		V
LEAK	Diode Leakage Current (reverse bias)	$V_{\text{DIODE}} = 3.3V$		0.1	1	μΑ
V _{SIG}	Signal Voltage Positive Clamp Negative Clamp	$I_{LOAD} = 10$ mA $I_{LOAD} = -10$ mA	5.6 -0.4	6.8 -0.8		V V
V _{ESD}	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD- 883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	Notes 2	±30 ±15			kV kV
f _c	Cut-off Frequency $Z_{\text{SOURCE}} = 50\Omega, Z_{\text{LOAD}} = 50\Omega$	R = 200Ω, C = 15pF; Note 3		100		MHz
A _{1GHz}	Absolute Attenuation @ 1GHz from 0dB Level	$Z_{\text{SOURCE}} = 50\Omega, Z_{\text{LOAD}} = 50\Omega,$ DC Bias = 0V; Notes 1 and 3		35		dB
A _{800MHz - 6GHz}	Absolute Attenuation @ 800MHz to 6GHz from 0dB Level	$Z_{\text{SOURCE}} = 50\Omega$, $Z_{\text{LOAD}} = 50\Omega$, DC Bias = 0V; Notes 1 and 35		30		dB

Note 1: $T_A=25$ °C unless otherwise specified.

Note 2: ESD applied to input and output pins with respect to GND, one at a time.

Note 3: Attenuation / RF curves characterized by a network analyzer using microprobes.

Performance Information

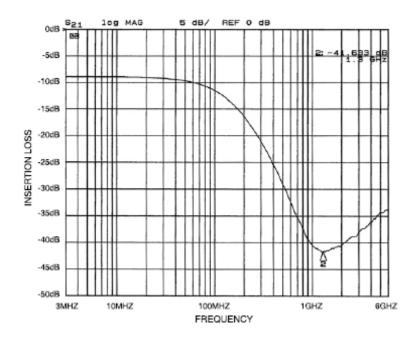


Figure 1. Insertion Loss vs. Frequency (FILTER1 Input to GND, CM1636-04DE)

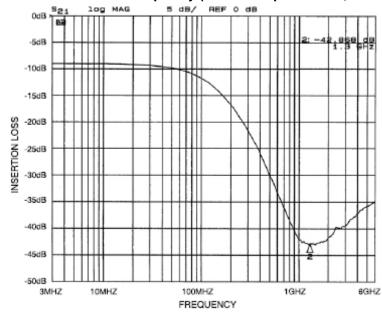


Figure 2. Insertion Loss vs. Frequency (FILTER2 Input to GND, CM1636-04DE)

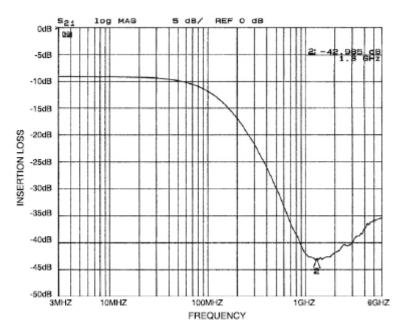


Figure 3. Insertion Loss vs. Frequency (FILTER3 Input to GND, CM1636-04DE)

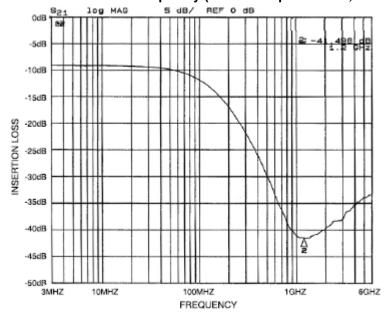


Figure 4. Insertion Loss vs. Frequency (FILTER4 Input to GND, CM1636-04DE)

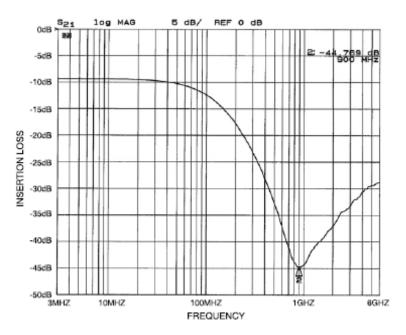


Figure 5. Insertion Loss vs. Frequency (FILTER1 Input to GND, CM1636-06DE)

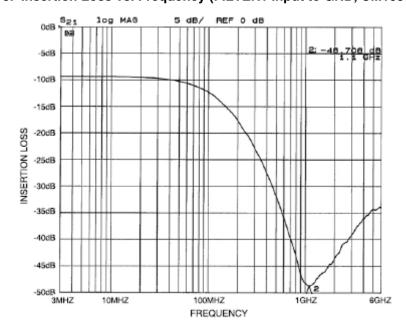


Figure 6. Insertion Loss vs. Frequency (FILTER2 Input to GND, CM1636-06DE)

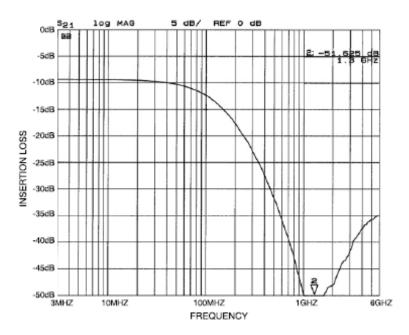


Figure 7. Insertion Loss vs. Frequency (FILTER3 Input to GND, CM1636-06DE)

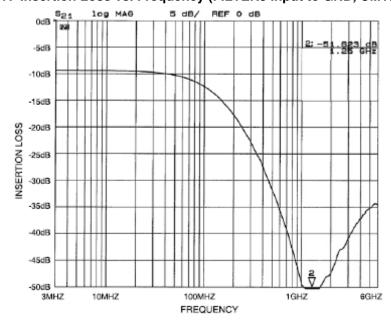


Figure 8. Insertion Loss vs. Frequency (FILTER4 Input to GND, CM1636-06DE)

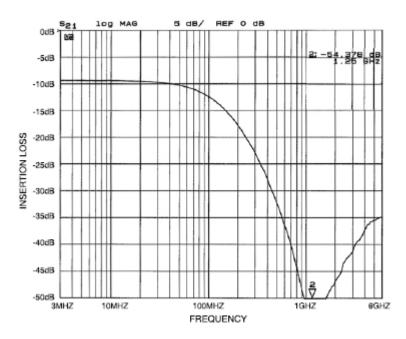


Figure 9. Insertion Loss vs. Frequency (FILTER5 Input to GND, CM1636-06DE)

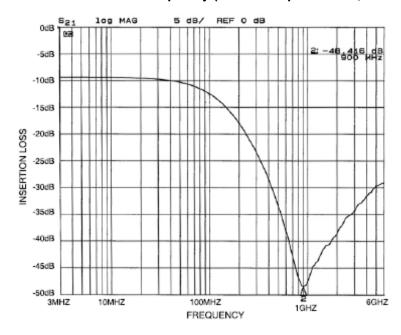


Figure 10. Insertion Loss vs. Frequency (FILTER6 Input to GND, CM1636-06DE)

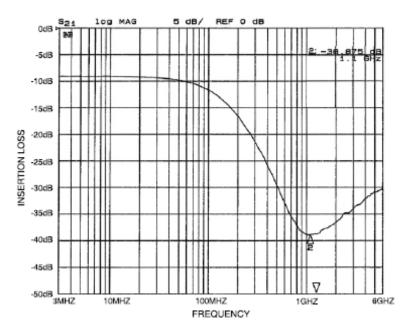


Figure 11. Insertion Loss vs. Frequency (FILTER1 Input to GND, CM1636-08DE)

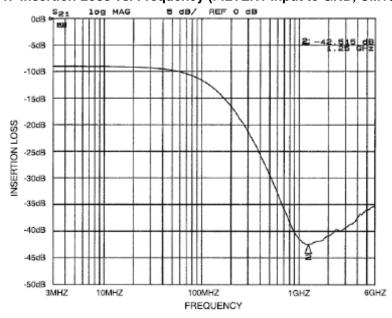


Figure 12. Insertion Loss vs. Frequency (FILTER2 Input to GND, CM1636-08DE)

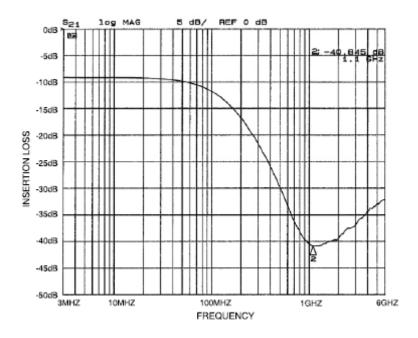


Figure 13. Insertion Loss vs. Frequency (FILTER3 Input to GND, CM1636-08DE)

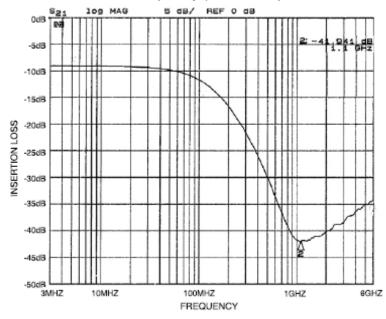


Figure 14. Insertion Loss vs. Frequency (FILTER4 Input to GND, CM1636-08DE)

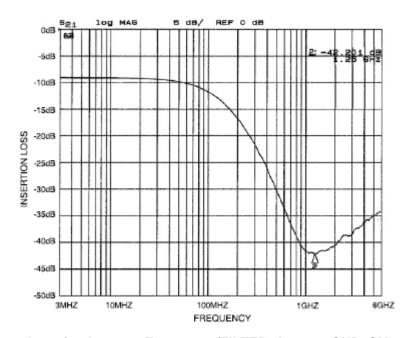


Figure 15. Insertion Loss vs. Frequency (FILTER5 Input to GND, CM1636-08DE)

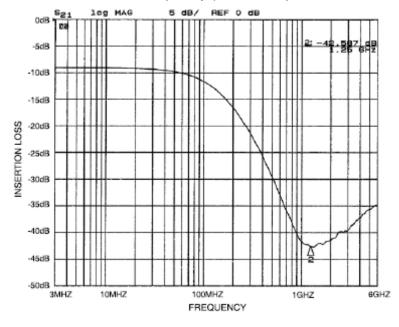


Figure 16. Insertion Loss vs. Frequency (FILTER6 Input to GND, CM1636-08DE)

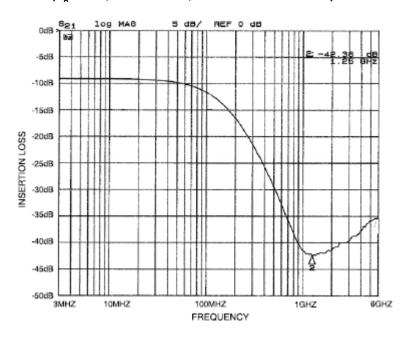


Figure 17. Insertion Loss vs. Frequency (FILTER7 Input to GND, CM1636-08DE)

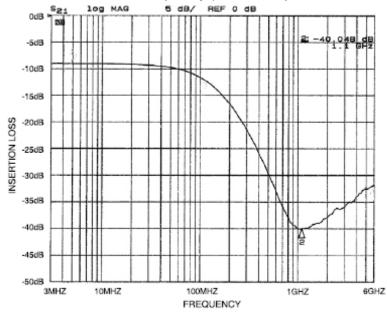


Figure 18. Insertion Loss vs. Frequency (FILTER8 Input to GND, CM1636-08DE)

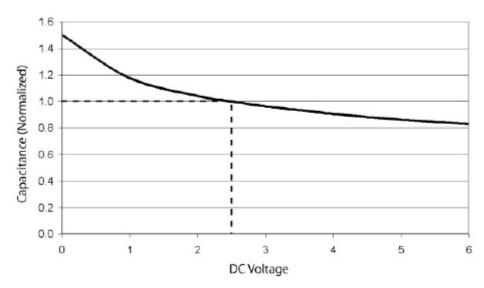


Figure 19. Filter Capacitance vs. Input Voltage over Temperature (normalized to capacitance at 2.5VDC and 25°C)

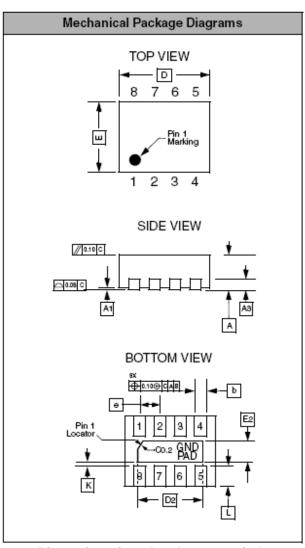
Mechanical Details

UDFN-08 Mechanical Specifications

Dimensions for the CM1636 supplied in a 8-lead, 0.4mm pitch UDFN package are presented below.

	PAC	KAGE	DIME	NSIO	NS				
Package		uDFN							
JEDEC No.			MO-2	229C*					
Leads				8					
Dim.	N	lillimete	rs		Inches				
Dilli.	Min	Nom	Max	Min	Nom	Max			
Α	0.45	0.50	0.55	0.018	0.020	0.022			
A 1	0.00	0.02	0.05	0.000	0.001	0.002			
А3	C).127 RE	F	O	.005 RE	:F			
b	0.15	0.20	0.25	0.006	0.008	0.010			
D	1.60	1.70	1.80	0.063	0.067	0.071			
D2	1.10	1.20	1.30	0.043	0.047	0.051			
E	1.25	1.35	1.45	0.049	0.053	0.057			
E2	0.30	0.40	0.50	0.012	0.016	0.020			
е	(0.40 BS	С	0	.016 BS	С			
К	(0.22 RE	F	O	.009 RE	:F			
L	0.15	0.25	0.35	0.006	0.010	0.014			
# per tape and reel			3000	pieces					
	Contro	olling din	nension:	millimet	ters				

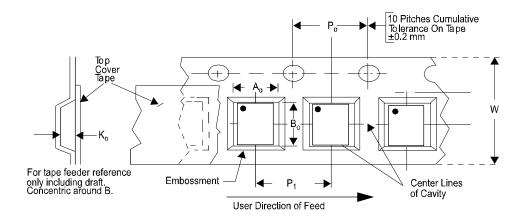
^{*}This package is compliant with JEDEC standard MO-229C with the exception of the D, D2, E, E2, K and L dimensions as called out in the table above.



Dimensions for 8-Lead, 0.4mm pitch uDFN package

Tape and Reel Specifications

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P ₁
CM1636-04DE	1.70 X 1.35 X 0.50	1.95 X 1.60 X 0.60	8mm	178mm (7")	3000	4mm	4mm



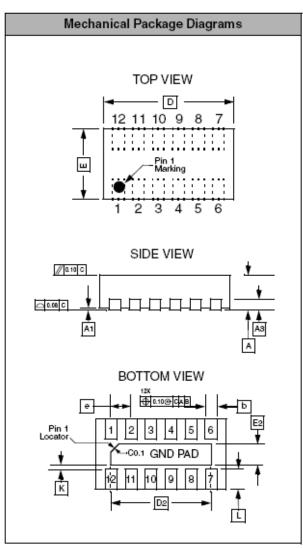
Mechanical Details (cont'd)

UDFN-12 Mechanical Specifications

Dimensions for the CM1636 suplied in a 12-lead, 0.4mm pitch UDFN package are presented below.

	PAC	KAGE	DIME	NSIO	NS				
Package		uDFN							
JEDEC No.			MO-2	229C*					
Leads			1	12					
Dim.	IV	lillimete	rs		Inches				
Diiii.	Min	Nom	Max	Min	Nom	Max			
Α	0.45	0.50	0.55	0.018	0.020	0.022			
A1	0.00	0.02	0.05	0.000	0.001	0.002			
А3	C).127 RE	F	O	.005 RE	:F			
b	0.15	0.20	0.25	0.006	0.008	0.010			
D	2.40	2.50	2.60	0.094	0.098	0.102			
D2	1.90	2.00	2.10	0.075	0.079	0.083			
E	1.25	1.35	1.45	0.049	0.053	0.057			
E2	0.30	0.40	0.50	0.012	0.016	0.020			
е	(0.40 BS	0	0	.016 BS	С			
к	(0.22 RE	F	0	.009 RE	:F			
L	0.15	0.25	0.35	0.006	0.010	0.014			
# per tape and reel		3000 pieces							
	Contro	olling din	nension:	millimet	ers				

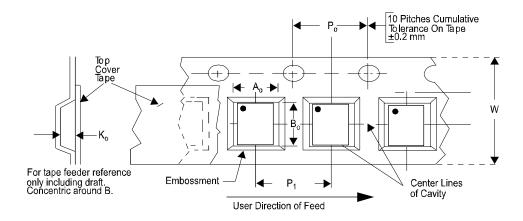
^{*}This package is compliant with JEDEC standard MO-229C with the exception of the D, D2, E, E2, K and L dimensions as called out in the table above.



Dimensions for 12-Lead, 0.4mm pitch uDFN package

Tape and Reel Specifications

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P ₁
CM1636-06DE	2.50 X 1.35 X 0.50	2.75 X 1.60 X 0.60	8mm	178mm (7")	3000	4mm	4mm



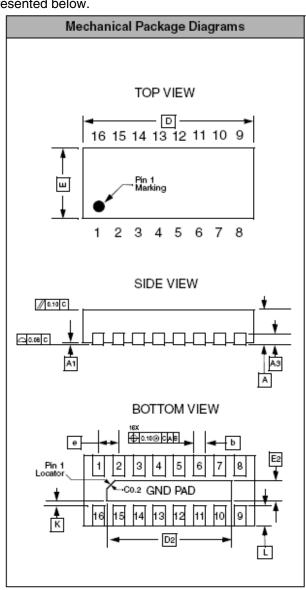
Mechanical Details (cont'd)

UDFN-16 Mechanical Specifications

Dimensions for the CM1636 suplied in a 16-lead, 0.4mm pitch UDFN package are presented below. The 16-lead, 0.4mm pitch uDFN package dimensions are presented below.

	PAC	KAGE	DIME	NSIO	NS				
Package		uDFN							
JEDEC No.			MO-	229C*					
Leads			1	16					
Dim.	IV	lillimete	rs		Inches				
Diiii.	Min	Nom	Max	Min	Nom	Max			
Α	0.45	0.50	0.55	0.018	0.020	0.022			
A1	0.00	0.02	0.05	0.000	0.001	0.002			
А3	C).127 RE	F	C	.005 RE	F			
b	0.15	0.20	0.25	0.006	0.008	0.010			
D	3.20	3.30	3.40	0.126	0.130	0.134			
D2	2.70	2.80	2.90	0.106	0.110	0.114			
E	1.25	1.35	1.45	0.049	0.053	0.057			
E2	0.30	0.40	0.50	0.012	0.016	0.020			
е	(0.40 BS	С	O	.016 BS	C			
к	(0.22 RE	F	C	.009 RE	F			
L	0.15	0.25	0.35	0.006	0.010	0.014			
# per tape and reel		3000 pieces							
	Contro	olling din	nension:	millime	ters				

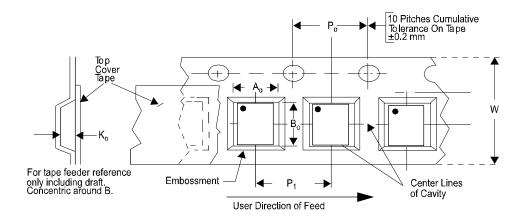
^{*}This package is compliant with JEDEC standard MO-229C with the exception of the D, D2, E, E2, K and L dimensions as called out in the table above.



Dimensions for 16-Lead, 0.4mm pitch uDFN package

Tape and Reel Specifications

PART NUMBER	PACKAGE SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P ₁
CM1636-08DE	3.30 X 1.35 X 0.50	3.50 X 1.55 X 0.70	12mm	178mm (7")	3000	4mm	4mm



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